CLAIMS

1. A resin-sprinkling method of sprinkling resin on a substantially circular resin-sprinkling area on a release film, wherein
resin is sprinkled by moving a drop point of the resin in a direction substantially coincident with a circumferential direction of the substantially circular resin-sprinkling area while dropping the resin on the resin-sprinkling area.

2. The method according to claim 1, wherein the resin is sprinkled while moving the drop point of the resin in a spiral fashion.

3. The method according to claim 1, wherein
the substantially circular resin-sprinkling area is separated into a plurality of virtual areas,
sprinkling of the resin is performed for each of the virtual areas on the resin-sprinkling area,
the virtual area is an area enclosed by an outer periphery, a center, and radiuses of the substantially circular resin-sprinkling area, and
the sprinkling of the resin within the virtual area is performed by moving the drop point of the resin in a serpentine manner within the virtual area from a center toward an outer edge of the resin-sprinkling area or from the outer edge toward the center of the resin-sprinkling area.

4. The method according to any one of claims 1 to 3, wherein a substantially circular frame is placed on the release film and the resin is sprinkled on an inside of the frame as the substantially circular resin-sprinkling area.

5. The method according to any one of claims 1 to 4, wherein movement of the drop point of the resin is performed by moving the release film so as to relatively move the drop point relative to the release film.

6. The method according to any one of claims 1 to 5, wherein the resin is sprinkled in a state where the release film is fixed on a film fixing base.

7. The method according to any one of claims 1 to 6, wherein the drop point of the resin is moved from the center toward the outer edge of the resin-sprinkling area or from the outer edge toward the center of the resin-sprinkling area while moving the drop point of the resin in the direction substantially coincident with the circumferential direction of the substantially circular resin-sprinkling area.

8. The method according to any one of claims 1 to 7, wherein a moving speed of the drop point of the resin is maintained substantially constant.

9. The method according to any one of claims 1 to 8, wherein an angular speed of the movement of the drop point of the resin slows down as reaching the outer edge from the center of the resin-sprinkling area.

10. The method according to any one of claims 1 to 9, wherein the movement of the drop point of the resin is controlled by a computer program.

11. The method according to any one of claims 1 to 10, wherein the resin is in a form of granule, powder, liquid, or paste.

12. A resin molding method, comprising:

a resin-sprinkling step of sprinkling resin on a resin-sprinkling area by the resin-sprinkling method according to any one of claims 1 to 11; and

a resin-molding step of molding the sprinkled resin on the release film.

13. The method according to claim 12, wherein

in the resin-molding step, at least one electronic component is resin-encapsulated.

14. A resin-sprinkling apparatus for conducting the resin-sprinkling method according to any one of claims 1 to 11, comprising:

a resin drop unit dropping resin on the resin-sprinkling area; and

a drop point movement unit moving the drop point of the resin in the direction substantially coincident with the circumferential direction of the substantially circular resin-sprinkling area.

15. The apparatus according to claim 14, wherein the drop point movement unit is a unit moving the drop point of the resin in a spiral fashion.

16. The apparatus according to claim 14, wherein

the substantially circular resin-sprinkling area includes a plurality of virtual areas,

the virtual area is an area enclosed by an outer periphery, a center, and radiuses of the substantially circular resin-sprinkling area,

the resin drop unit is a unit dropping the resin for each of the virtual areas, and

the drop point movement unit is a unit moving the drop point of the resin in a serpentine manner within the virtual area from a center toward an outer edge of the resin-sprinkling area or from the outer edge toward the center of the resin-sprinkling area.

17. The apparatus according to any one of claims 14 to 16, further comprising:

a substantially circular frame, wherein

the substantially circular frame is placed on the release film, and

the resin drop unit is a unit dropping the resin on an inside of the frame as the substantially circular resin-sprinkling area.

18. The apparatus according to any one of claims 14 to 17, wherein the drop point movement unit is a unit moving the release film so as to relatively move the drop point relative to the release film.

19. The apparatus according to any one of claims 14 to 18, further comprising: a film fixing base, wherein the release film is fixed on the film fixing base.

20. The apparatus according to claim 19, wherein the drop point movement unit is a unit moving the film fixing base together with the release film so as to relatively move the drop point relative to the release film.

21. The apparatus according to any one of claims 14 to 19, wherein the drop point movement unit is a unit moving the drop point of the resin from the center toward the outer edge of the resin-sprinkling area or from the outer edge toward the center of the resin-sprinkling area while moving the drop point of the resin in the direction substantially coincident with the circumferential direction of the substantially circular resin-sprinkling area.

22. The apparatus according to any one of claims 14 to 21, wherein the drop point movement unit is a unit maintaining a moving speed of the drop point of the resin substantially constant.

23. The apparatus according to any one of claims 14 to 22, wherein the drop point movement unit is a unit slowing down an angular speed of movement of the drop point of the resin as reaching the outer edge from the center of the resin-sprinkling area.